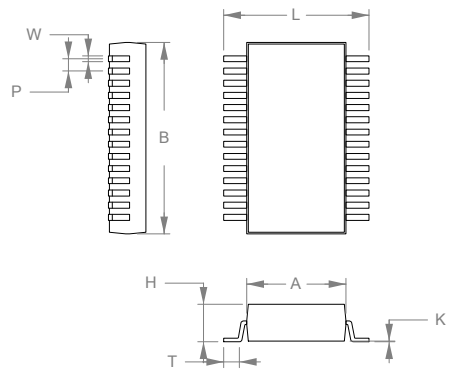


Component (Fig. 1)

Small Outline IC (SOIC)

Pitch.....	0.65
Pin Package.....	28
Pin Count.....	28
Lmin.....	7.60
Lmax.....	7.90
Tmin.....	0.63
Tmax.....	1.03
Wmin.....	0.25
Wmax.....	0.38
Amin.....	5.20
Amax.....	5.40
Bmin.....	10.00
Bmax.....	10.40
Hmax.....	2.00
Kmin.....	0.05

Fig.1

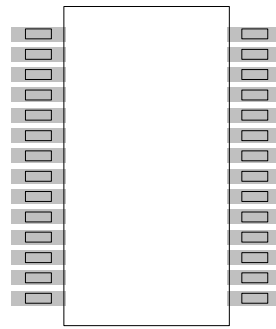


Solder Joint Goals (Fig. 2)

Environment is B - NOMINAL

Toe (Outside) Goal.....	0.35
Toe min.....	0.36
Toe max.....	0.53
Heel (Inside) Goal.....	0.35
Heel Min.....	0.30
Heel max.....	0.63
Side Goal.....	0.03
Side Min.....	0.00
Side max.....	0.10

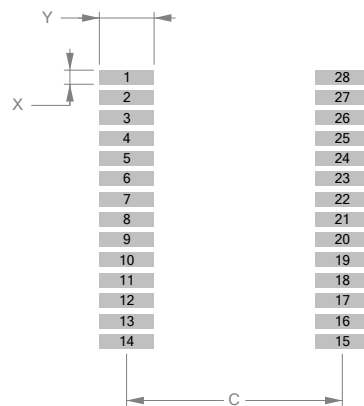
Fig.2



Land Pattern (Fig. 3)

Pitch.....	0.65
C.....	6.90
Y.....	1.75
X.....	0.45

Fig.3



Silkscreen (Fig. 4)

R1.....4.50
 R2.....10.20

Assembly (Fig. 5)

Anom.....5.30
 Bnom.....10.20

Courtyard (Fig. 6)

V1.....9.20
 V2.....10.90

Program Version: 2009.19.02

Advisories

Land is being trimmed for
 lands that extend under the
 body.

Land is being trimmed
 to maintain side pad to pad
 clearance.

Fig.4

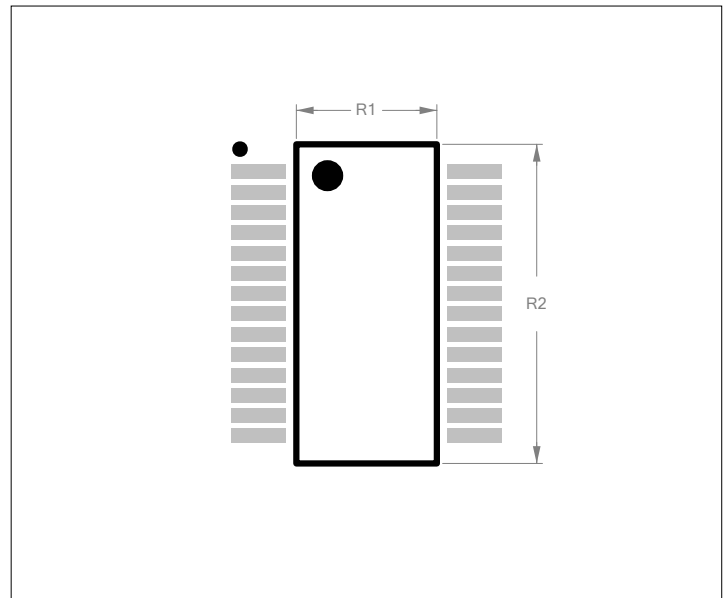


Fig.5

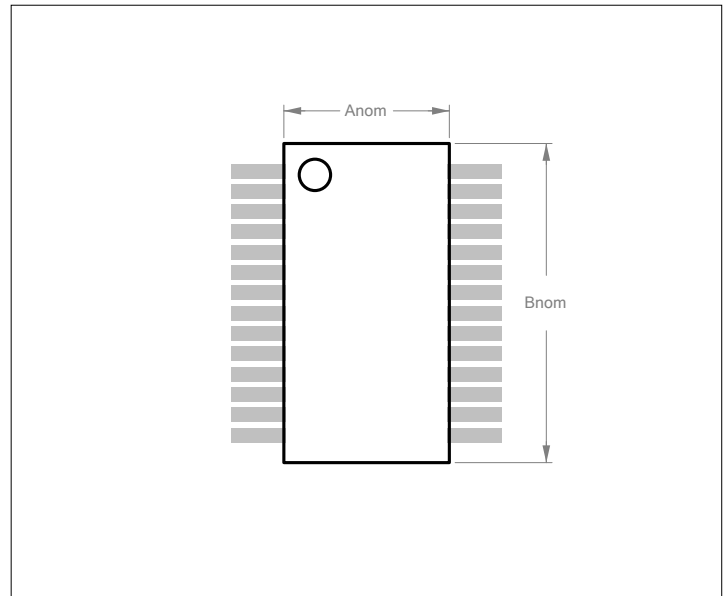


Fig.6

